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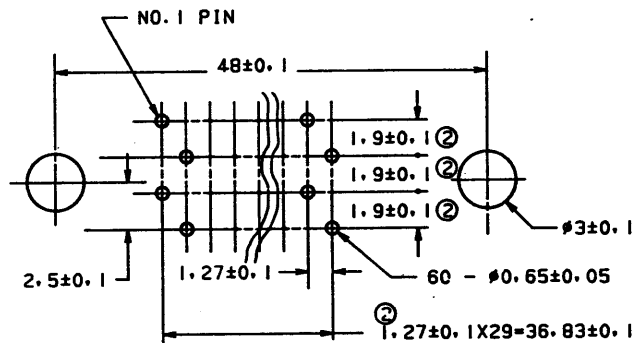
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2

1

PRODUCT NO	HOUSING COLOR	Au PLATING THK.
69740-001	WHITE	0.1 μ m MIN
69740-002	BLACK	0.1 μ m MIN
69740-101	WHITE	0.76 μ m MIN
69740-102	BLACK	0.76 μ m MIN

REVISIONS			
REV	DESCRIPTION	BY	DATE
	SEE 1 OF 2		



RECOMMENDED MOUNTING DIMENSION (TOP VIEW)

NOTES:

①. MATERIAL AND FINISH:

PIN

MATERIAL - PHOS. BRO.
 FINISH - ALL OVER Ni UNDERPLATING 0.5 μ m THK MIN.
 CONTACT AREA - Au PLATING (THK. SEE TABLE),
 OVER Pd-Ni PLATING 0.5 μ m THK MIN.

SOLDER TAIL - SnPb(9/1) PLATING 3.8 μ m THK MIN.

CAP HOUSING (R/A)

MATERIAL - 66 NYLON GLASS 25% FILLED, UL94V-0.

②. TO BE NONCUMULATIVE TOLERANCE.

③. PIN RETENTION FORCE 0.5Kg/PIN MIN.

④. TO BE SYMMETRY WITHIN ± 0.1 ABOUT DATUM B.

⑤. TO BE SYMMETRY WITHIN ± 0.1 ABOUT DATUM C.

⑥. TO BE SYMMETRY WITHIN ± 0.3 ABOUT DATUM D.

SHEET INDEX		ISSUE																		CUSTOMER COPY		DuPont Electronics		
		SH NO	I																	CODE IDENT	DATE			
																				22526	09/21/87	TITLE IC CARD CONNECTOR 60 POS. CAP ASS'Y (R/A)		
																				SEE NOTE ①	CHK			10/2/87
																				SEE NOTE ①	ENGR	10/2/87	SCALE SIZE DWG NO 5-1 C 69740	
																				APPD	10/5/87	CAD CUST SHEET 2 OF 2		
LEVELS		DO NOT SCALE DRAWING		TOLERANCE UNLESS OTHERWISE NOTED MM/INCH ± 0.3																MATERIAL				DATE
				THIRD ANGLE PROJECTION 																DR M. KITAMURA		09/21/87		
TABULATION SHEETS REQUIRED		YES NO		LINEAR 0.0000-0.2517-0000-0020 0.0000-0.137000-0005 0.0000-0.2517-0000-0020																FINISH		10/2/87		
				ANGLES $\pm 2^{\circ}$ $\pm 5^{\circ}$																APPD		10/5/87		